SDAS206A - APRIL 1982 - REVISED DECEMBER 1994

- Permit Multiplexing From n Lines to One Line
- Perform Parallel-to-Serial Conversion
- Strobe (Enable) Line Provided for Cascading (n Lines to n Lines)
- 'ALS253 and SN74AS253A Are 3-State Versions of These Parts
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

#### description

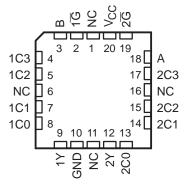
These dual 1-of-4 data selectors/multiplexers contain inverters and drivers to supply full binary decoding data selection to the AND-OR gates. Separate strobe ( $\overline{G}$ ) inputs are provided for each of the two 4-line sections.

The SN54ALS153 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to 125°C. The SN74ALS153 and SN74AS153 are characterized for operation from 0°C to 70°C.

SN54ALS153 . . . J PACKAGE SN74ALS153, SN74AS153 . . . D OR N PACKAGE (TOP VIEW)

,		VIL	,		
1G [ B [ 1C3 [ 1C2 [ 1C1 [ 1C0 [ 1Y [ GND ]	2 3 4 5 6 7	υ	14 13 12 11		V <u>C</u> C 2G A 2C3 2C2 2C1 2C0 2Y
	Ľ		Ũ	٢	

SN54ALS153 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

		INP	UTS			070005	
SEL	ECT		DA	TA		STROBE G	OUTPUT
В	Α	C0	C1	C2	C3	Ŭ	I
Х	Х	Х	Х	Х	Х	Н	L
L	L	L	Х	Х	Х	L	L
L	L	Н	Х	Х	Х	L	Н
L	Н	Х	L	Х	Х	L	L
L	н	Х	Н	Х	Х	L	н
н	L	Х	Х	L	Х	L	L
н	L	Х	Х	Н	Х	L	Н
н	Н	Х	Х	Х	L	L	L
н	Н	Х	Х	Х	Н	L	н

FUNCTION TABLE

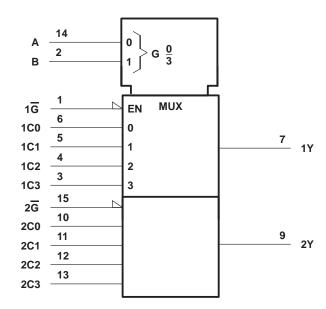
Select inputs A and B are common to both sections.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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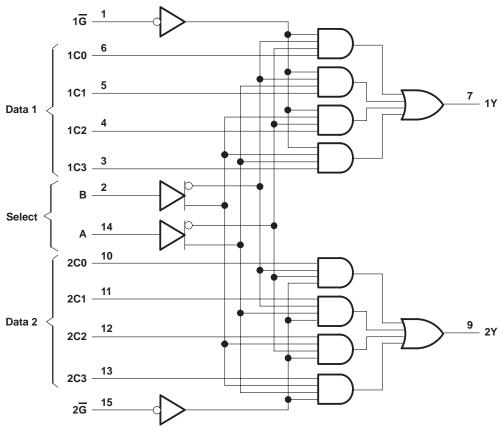
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#### logic symbol<sup>†</sup>



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

#### logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.



SDAS206A - APRIL 1982 - REVISED DECEMBER 1994

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Operating free-air temperature range, T <sub>A</sub> :	SN54ALS153	–55°C to 125°C
	SN74ALS153	0°C to 70°C
Storage temperature range		–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		SN	54ALS1	53	SN74ALS153			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ЮН	High-level output current			-1			-2.6	mA
IOL	Low-level output current			12			24	mA
ТА	Operating free-air temperature	-55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	7507.0	TEST CONDITIONS			53	SN	74ALS1	53	
PARAMETER	TEST C	ONDITIONS	MIN	TYP‡	MAX	MIN	typ‡	MAX	UNIT
VIK	V <sub>CC</sub> = 4.5 V,	l <sub>l</sub> = –18 mA			-1.5			-1.5	V
	$V_{CC}$ = 4.5 V to 5.5 V,	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> -2	2		V <sub>CC</sub> -2	2		
VOH		$I_{OH} = -1 \text{ mA}$	2.4	3.3					V
	V <sub>CC</sub> = 4.5 V	$I_{OH} = -2.6 \text{ mA}$				2.4	3.2		
		I <sub>OL</sub> = 12 mA		0.25	0.4		0.25	0.4	V
V <sub>OL</sub>	$V_{CC} = 4.5 V$	I <sub>OL</sub> = 24 mA					0.35	0.5	V
lį	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 7 V			0.1			0.1	mA
ΙIΗ	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20			20	μΑ
١ <sub>١</sub> ٢	V <sub>CC</sub> = 5.5 V,	VI = 0.4 V			-0.1			-0.1	mA
١ <sub>O</sub> §	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-20		-112	-30		-112	mA
ICC	V <sub>CC</sub> = 5.5 V,	All inputs at 4.5 V		7.5	14		7.5	14	mA

<sup>‡</sup> All typical values are at V<sub>CC</sub> = 5 V,  $T_A = 25^{\circ}C$ .

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



SDAS206A - APRIL 1982 - REVISED DECEMBER 1994

#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CL	= 50 pl = 500 0 = MIN t	V to 5.5 <del>,</del> 2, o MAX <sup>†</sup> SN74A		UNIT
			MIN	MAX	MIN	MAX	
tPLH			5	29	5	21	
<sup>t</sup> PHL	A or B	Y	5	27	5	21	ns
<sup>t</sup> PLH	Data	N N	3	15	3	10	
<sup>t</sup> PHL	(any C)	Y	2	18	4	15	ns
<sup>t</sup> PLH	G	v	5	27	5	18	200
<sup>t</sup> PHL	6	T	3	22	5	18	ns

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>‡</sup>

Supply voltage, V <sub>CC</sub>	V
Input voltage, V <sub>1</sub>	V
Operating free-air temperature range, T <sub>A</sub> : SN74AS153 0°C to 70°	С
Storage temperature range	С

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		SI	174AS15	3	
		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
IOH	High-level output current			-15	mA
IOL	Low-level output current			48	mA
Т <sub>А</sub>	Operating free-air temperature	0		70	°C



SDAS206A - APRIL 1982 - REVISED DECEMBER 1994

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONE	DITIONS	MIN	TYP†	MAX	UNIT	
VIK		V <sub>CC</sub> = 4.5 V,	lj = – 18 mA			-1.2	V	
		$V_{CC} = 4.5 V \text{ to } 5.5 V,$	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2				
VOH	[	V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = – 15 mA	2.4	3.2		V	
VOL		V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 48 mA		0.35	0.5	V	
	А, В		N/ <b>-</b> N/			0.2		
Ц	All others	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 7 V			0.1	mA	
	А, В					40		
ЧΗ	All others	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V		4		μA	
	А, В					-1		
ΊL	All others	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 0.4 V			-0.5	mA	
10‡		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	mA	
ІССН		V <sub>CC</sub> = 5.5 V			16	26	mA	
ICCL		V <sub>CC</sub> = 5.5 V			21	33	mA	

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> =  $25^{\circ}$ C.

<sup>‡</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

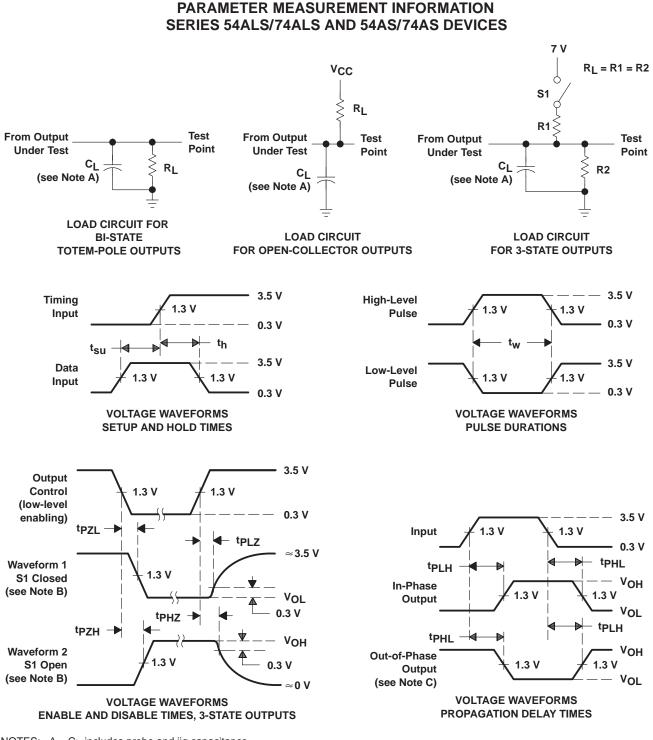
#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	ТО (OUTPUT)	R <sub>L</sub> = 500 s T <sub>A</sub> = MIN	V to 5.5 V, F, Ω, to MAX§ AS153 MAX	UNIT
tPLH			3	12.5	
tPHL	A or B	Y	3	11	ns
<sup>t</sup> PLH	Data		2	7	
<sup>t</sup> PHL	(any C)	Y	2	8	ns
<sup>t</sup> PLH	G	×	3	11.5	ns
<sup>t</sup> PHL	5	Ĩ	10	9	115

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



SDAS206A - APRIL 1982 - REVISED DECEMBER 1994



NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
   C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR  $\leq$  1 MHz, t<sub>f</sub> = t<sub>f</sub> = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

#### Figure 1. Load Circuits and Voltage Waveforms





25-Sep-2013

### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
84134012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84134012A SNJ54ALS 153FK	Samples
8413401EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8413401EA SNJ54ALS153J	Samples
8413401FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8413401FA SNJ54ALS153W	Samples
SN54ALS153J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS153J	Samples
SN74ALS153D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS153	Samples
SN74ALS153DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS153	Samples
SN74ALS153DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS153	Samples
SN74ALS153DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS153	Samples
SN74ALS153DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS153	Samples
SN74ALS153DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS153	Samples
SN74ALS153N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS153N	Samples
SN74ALS153NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS153N	Samples
SN74ALS153NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS153	Samples
SN74ALS153NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS153	Samples
SN74ALS153NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS153	Samples
SN74AS153D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS153	Samples
SN74AS153DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS153	Samples



25-Sep-2013

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AS153DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS153	Samples
SN74AS153N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS153N	Samples
SN74AS153NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS153N	Samples
SN74AS153NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS153	Samples
SN74AS153NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS153	Samples
SN74AS153NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS153	Samples
SNJ54ALS153FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84134012A SNJ54ALS 153FK	Samples
SNJ54ALS153J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8413401EA SNJ54ALS153J	Samples
SNJ54ALS153W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8413401FA SNJ54ALS153W	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



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25-Sep-2013

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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#### OTHER QUALIFIED VERSIONS OF SN54ALS153, SN74ALS153 :

• Catalog: SN74ALS153

• Military: SN54ALS153

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# PACKAGE MATERIALS INFORMATION

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#### TAPE AND REEL INFORMATION

#### REEL DIMENSIONS

TEXAS INSTRUMENTS





TAPE AND REEL INFORMATION

#### TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

All dimensions are nomina	I											
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS153DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74ALS153NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS153NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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# PACKAGE MATERIALS INFORMATION

14-Jul-2012



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS153DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74ALS153NSR	SO	NS	16	2000	367.0	367.0	38.0
SN74AS153NSR	SO	NS	16	2000	367.0	367.0	38.0

J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N\*\*) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a metal lid.

D. Falls within JEDEC MS-004



# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

# D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



### MECHANICAL DATA

#### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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